

Features

- Current:5-300A,Voltage:100-1600V
- All models feature the same compact dimensions to Provide auniform mounting pitch
- Glass passivated diode chip
- Excellent power/volume ratio,High thermal conductivity Package, electrically insulated case

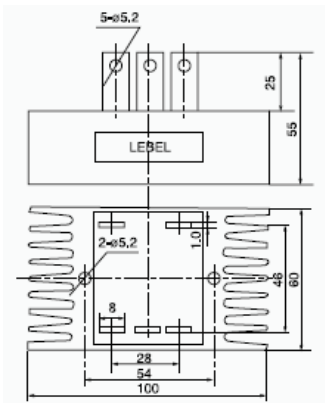
| | |
|-------------|-----------|
| $I_{F(AV)}$ | 50-100A |
| V_{RRM} | 100-1600V |
| V_F | 1.1V |
| I_{FSM} | 400A |

Typical Applications

- Eliminator supply,industrial automatic control
- Numierial-controlled machinery,telecontrol system

| SYMBOL | CHARACTERISTIC | TEST CONDITIONS | VALUE | | UNIT |
|---------------|--------------------------------------|--|-------|------|------|
| | | | Min | Max | |
| $I_{F(AV)}$ | Mean forward current | 180 ° sine wave, 50HZ Double side cooled, THS=55°C | 50 | 100 | A |
| V_{RRM} | Repetitive peak reverse voltage | $V_{DRM}\&V_{RRM}$ tp=10ms $V_{DSM}\&V_{RSM}=V_{DRM}\&V_{RRM}+100V$ | 100 | 1600 | V |
| V_{RMS} | RMS current | | 70 | 860 | V |
| V_{DC} | DC blocking voltage | | 100 | 1600 | V |
| I_{FSM} | Surge on-state current | sine wave | | 400 | A |
| V_F | Diode forward voltage | $I_F=17.5A$ | | 1.1 | V |
| I_R | Reverse leakage current | $T_a=25^\circ C$ | | 10 | uA |
| $I_{R(H)}$ | | $T_a=100^\circ C$ | | 200 | uA |
| $R_{th(j-c)}$ | Thermal impedance node to the shell | 180 ° sine wave, single heat sink | | 5.0 | °C/W |
| $R_{th(c-a)}$ | Thermal impedance (shell to powder) | 180 ° sine wave, single heat sink | | 8 | °C/W |
| V_{iso} | Insulation voltage | | 2500 | | V |
| T_J | Stored temperature | | -40 | 125 | °C |
| T_{stq} | Stored temperature | | -40 | 150 | °C |
| W_t | Weight | | | 315 | g |
| Outline | | | | | |

Outline



Circuit Drawing:

